

I Claim:

1. A cooling system for cooling a circuit board including a first heat source and a second heat source, comprising:

cooling apparatus configured to absorb heat dissipated from the first and second heat sources; and

5 an actuator configured to actuate the cooling apparatus into conforming thermal contact with the first and second heat sources on the circuit board.

2. The cooling system of claim 1, wherein:

the cooling apparatus comprises a first cooled body and a second cooled body;

the actuator is configured to actuate the first cooled body into conforming thermal contact with the first heat source; and

5 the actuator is further configured to actuate the second cooled body into conforming thermal contact with the second heat source.

3. The cooling system of claim 2, wherein:

the actuator comprises a support configured to retractably actuate toward and away from the circuit board; and

the first and second cooled bodies are compliantly mounted to the support.

4. The cooling system of claim 1, wherein the cooling apparatus comprises a thermally conductive body composed of a compliant material, and wherein the cooling apparatus adaptively conforms to the first and second heat sources to compensate for any differences in their height with respect to the circuit board.

5. The cooling system of claim 4, wherein the cooling apparatus defines a non-planar surface that substantially conforms to the height of the first and second heat sources with respect to the circuit board.

6. The cooling system of claim 1, and further including a third heat source, the first heat source and the second heat source being on a first side of the circuit board, and the third heat source being on a second side of the circuit board and further comprising:

a second cooling apparatus configured to absorb heat dissipated from the third heat source; and

a second actuator configured to actuate the second cooling apparatus into conforming thermal contact with the third heat source on the circuit board.

7. The cooling system of claim 6, wherein:

the first cooling apparatus comprises a first cooled body and a second cooled body;

the second cooling apparatus comprises a third cooled body;

the first actuator is configured to actuate the first cooled body into conforming thermal contact with the first heat source;

the first actuator is further configured to actuate the second cooled body into conforming thermal contact with the second heat source; and

the second actuator is configured to actuate the third cooled body into conforming thermal contact with the third heat source.

8. The cooling system of claim 7, wherein:

the first actuator comprises a first support configured to retractably actuate toward and away from the first side of the circuit board;

the first and second cooled bodies are compliantly mounted to the first support;

the second actuator comprises a second support configured to retractably actuate toward and away from the second side of the circuit board; and

the third cooled body is compliantly mounted to the second support.

9. The cooling system of claim 6, wherein the first and second cooling apparatuses each comprise a thermally conductive body composed of a compliant material, and wherein the first cooling apparatus adaptively conforms to the first and second heat

Cont
Sub B1

10005107-2

sources to compensate for any differences in their height with respect to the circuit board.

10. The cooling system of claim 9, wherein the first cooling apparatus defines a non-planar surface that substantially conforms to the height of the first and second heat sources with respect to the circuit board.

11. A cooling system for cooling a circuit board including a first heat source and a second heat source, comprising:

a means for absorbing heat dissipated from the first and second heat sources; and
a means for actuating the means for absorbing into conforming thermal contact

with the first and second heat sources on the circuit board.

12. The cooling system of claim 11, wherein:

the means for absorbing comprises a first cooled body and a second cooled body;
the means for actuating is configured to actuate the first cooled body into
conforming thermal contact with the first heat source; and

the means for actuating is further configured to actuate the second cooled body
into conforming thermal contact with the second heat source.

13. The cooling system of claim 11, wherein the means for actuating is configured to retractably actuate toward and away from the circuit board.

14. A method for cooling a circuit board including a first heat source and a second heat source, comprising:

retractably actuating an actuator carrying a means for absorbing heat such that the
means for absorbing heat is moved into conforming thermal contact with the first and
second heat sources on the circuit board.

absorbing heat dissipated from the first and second heat sources using the means
for absorbing heat.

15. The method of claim 14, wherein:

the means for absorbing comprises a first cooled body and a second cooled body;

and

in the step of retractably actuating, the actuator is configured to actuate the first cooled body into conforming thermal contact with the first heat source, and the means for actuating is further configured to actuate the second cooled body into conforming thermal contact with the second heat source.

Cond
Sub 1.1

5

10005107-2

10005107-2